Product Change Notification - RMES-28HUEN707

Date: 05 Apr 2017

Product Category: Linear Regulators

Notification subject: CCB 2882 and CCB 2883 Initial Notice: Qualification of JCET as an additional assembly site for selected products of 135K DLM wafer technology available in 3L SOT-23A package using (CuPdAu) bond wire.

Notification text:

PCN Status:
Initial notification.

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of JCET as an additional assembly site for selected products of 135K DLM wafer technology available in 3L SOT-23A package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:
Assembled at HANA and LPI using gold (Au) bond wire and G600 molding compound material.

Post Change:
Assembled at HANA and LPI using gold (Au) bond wire and G600 molding compound material or
Assembled at JCET using palladium coated copper with gold flash (CuPdAu) bond wire and GE-1030S or EMG 600-2 molding compound material.

Pre and Post Change Summary:

	Pre Change		Post Change		
Assembly Site	HANA	LPI	HANA	LPI	JCET
Wire material	Au wire	Au wire	Au wire	Au wire	CuPdAu wire
Die attach material	8006NS	84-3J	8006NS	84-3J	8006NS
Molding compound material	G600	G600	G600	G600	*GE-1030S or EMG 600-2
Lead frame material	A194	EFTEC64T	A194	EFTEC64T	A194

*Note: Microchip will run qualify using both mold compound materials but after qualification will select the mold compound that performs the best and only use one mold compound. The final PCN will identify the mold compound that will be used.

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at JCET assembly site.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:
June 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2017					-->	June 2017				
Workweek	14	15	16	17	18		22	23	24	25	26
Initial PCN Issue Date	X										
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
April 04, 2017: Issued initial notification.
April 05, 2017: Corrected typographical error on the revision history from March to April.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-28HUEN707_Affected_CPN.pdf
PCN_RMES-28HUEN707_Qual Plan.pdf
PCN_RMES-28HUEN707_Affected_CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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Affected Catalog Part Numbers (CPN)

PCN_RMES-28HUEN707
CATALOG_PART_NBR
MCP1702T-1202E/CB
MCP1702T-1502E/CB
MCP1702T-1802E/CB
MCP1702T-2102E/CB
MCP1702T-2202E/CB
MCP1702T-2302E/CB
MCP1702T-2502E/CB
MCP1702T-2702E/CB
MCP1702T-2802E/CB
MCP1702T-3002E/CB
MCP1702T-3302E/CB
MCP1702T-3602E/CB
MCP1702T-4002E/CB
MCP1702T-4101E/CB
MCP1702T-4502E/CB
MCP1702T-4702E/CB
MCP1702T-5002E/CB
MCP1702T-5102E/CB
MCP1703AT-1202E/CB
MCP1703AT-1502E/CB
MCP1703AT-1802E/CB
MCP1703AT-2052E/CB
MCP1703AT-2502E/CB
MCP1703AT-2802E/CB
MCP1703AT-3002E/CB
MCP1703AT-3152E/CB
MCP1703AT-3302E/CB
MCP1703AT-3302E/CBAAC
MCP1703AT-3502E/CB
MCP1703AT-4002E/CB
MCP1703AT-5001E/CB
MCP1703AT-5001E/CBAAA
MCP1703AT-5002E/CB
MCP1703T-1202E/CB
MCP1703T-1502E/CB
MCP1703T-1802E/CB
MCP1703T-2402E/CB
MCP1703T-2502E/CB
MCP1703T-2802E/CB
MCP1703T-3002E/CB
MCP1703T-3301E/CB
MCP1703T-3302E/CB

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Affected Catalog Part Numbers (CPN)

PCN_RMES-28HUEN707
CATALOG_PART_NBR
MCP1703T-3502E/CB
MCP1703T-3602E/CB
MCP1703T-4002E/CB
MCP1703T-4502E/CB
MCP1703T-5001E/CB
MCP1703T-5002E/CB
MCP1703T-5002E/CBHAZ